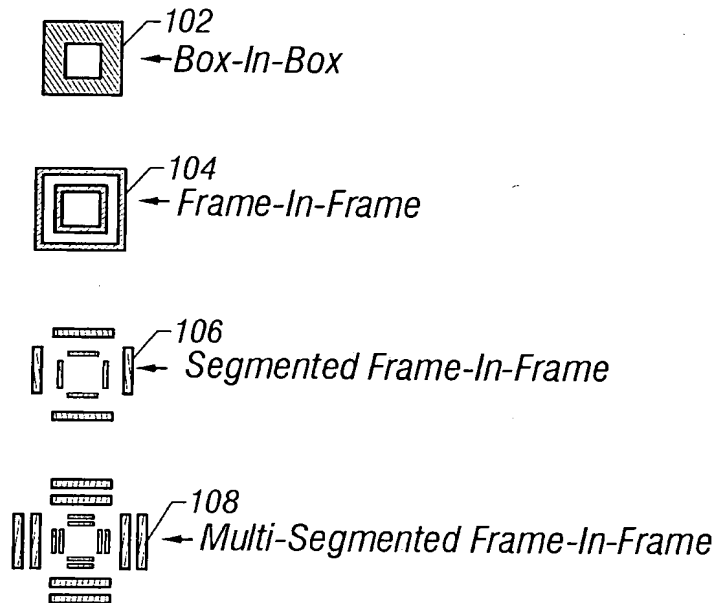
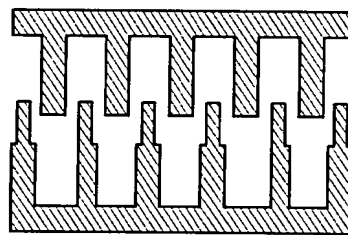


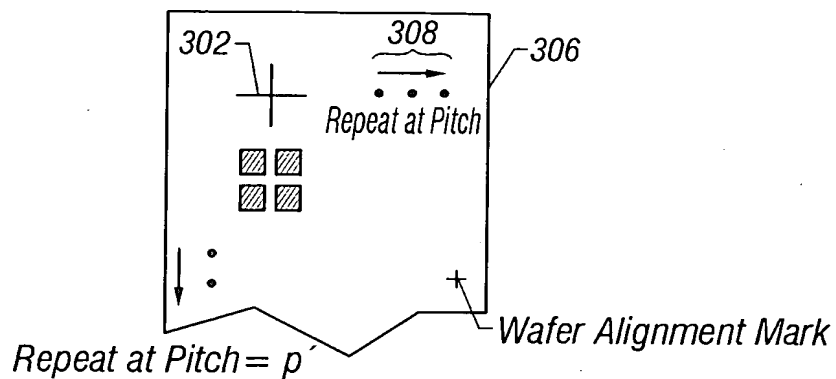
Heller Ehrman White & McAuliffe LLP  
Title: "REFERENCE WAFER AND PROCESS FOR  
MANUFACTURING SAME"  
Inventor(s): A. Smith et al.  
Atty Docket No.: 38203-6081B  
Application No.: 10/765,223 - Filed: 01/26/2004  
1/19



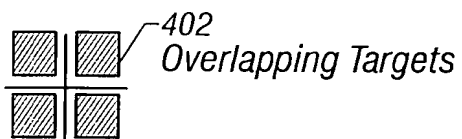
**FIG. 1**



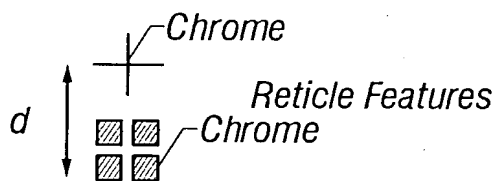
**FIG. 2**



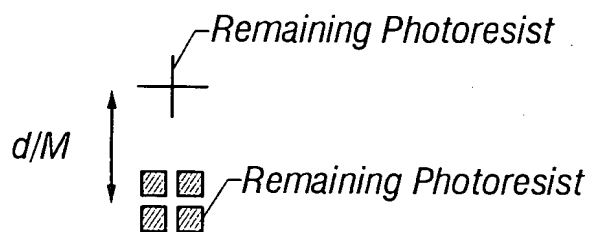
**FIG. 3**



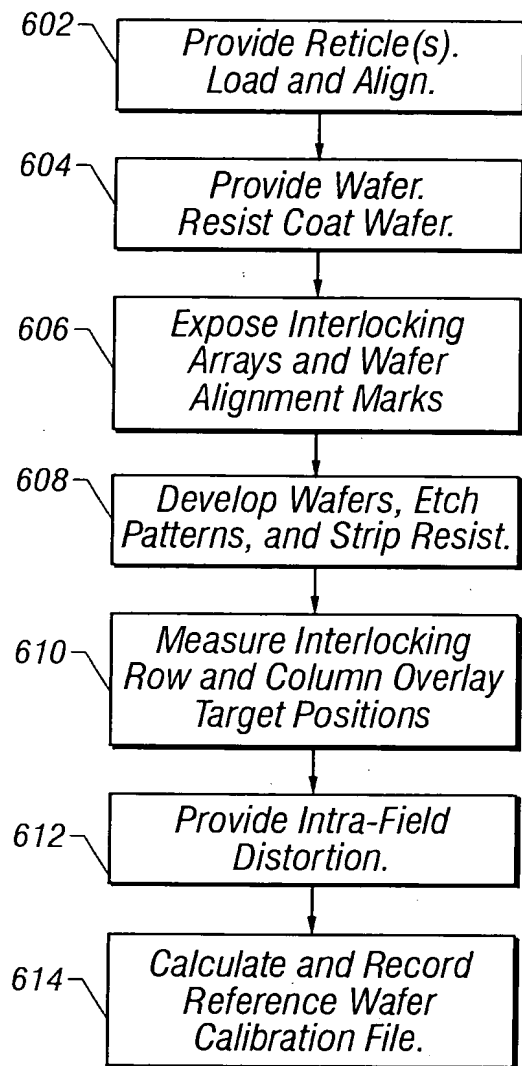
**FIG. 4**



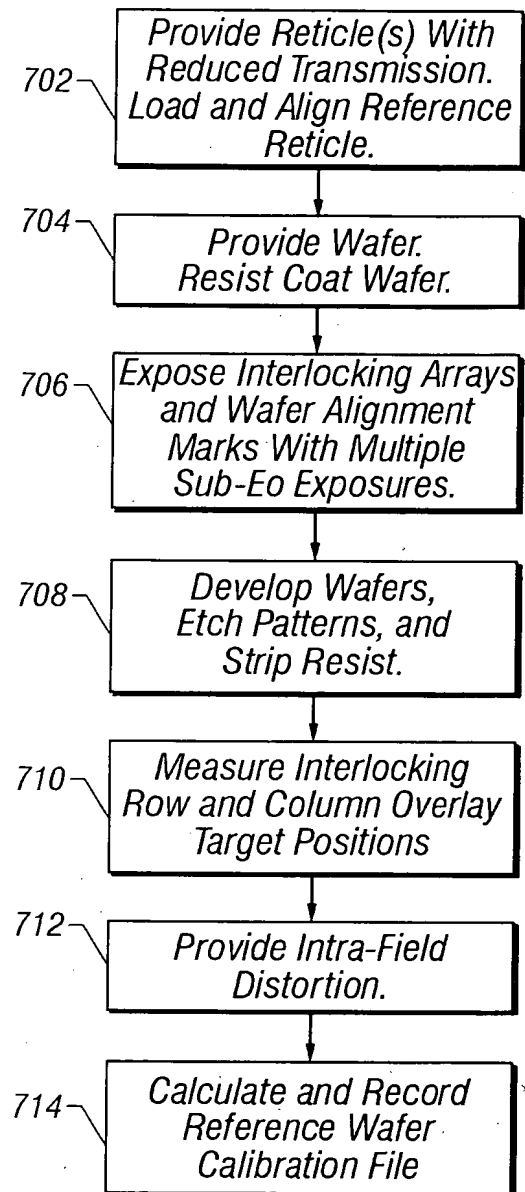
**FIG. 5A**



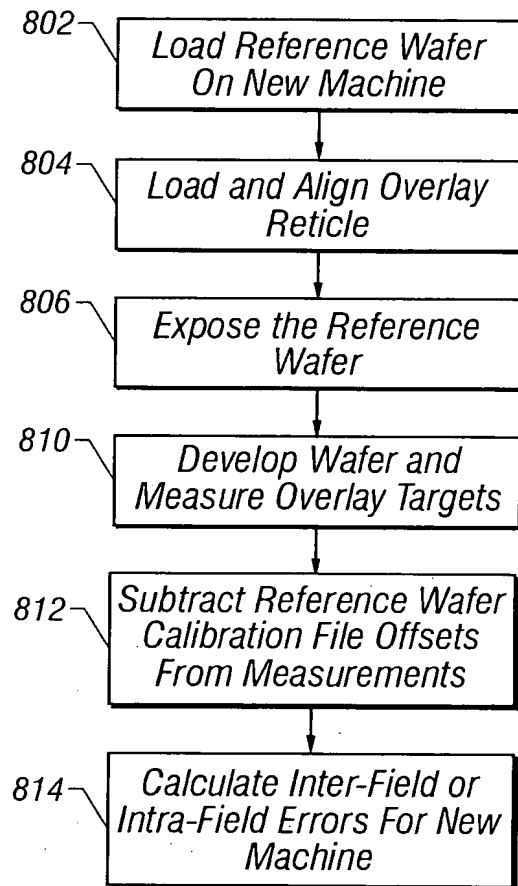
**FIG. 5B**



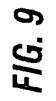
**FIG. 6**



**FIG. 7**



**FIG. 8**



**FIG. 9**

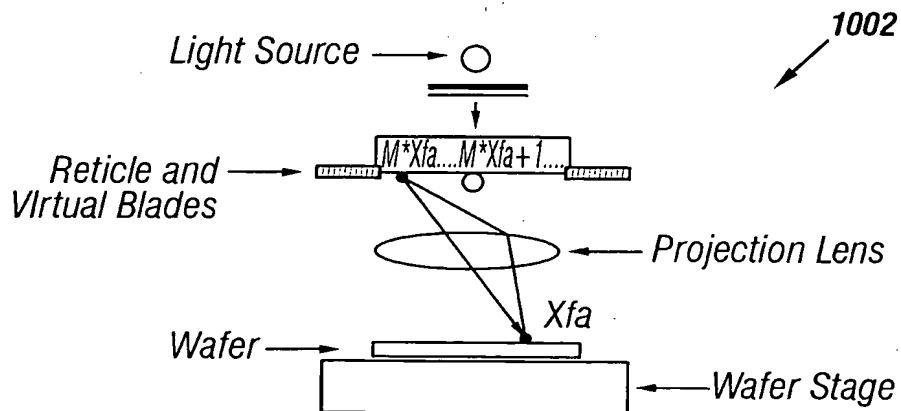


FIG. 10

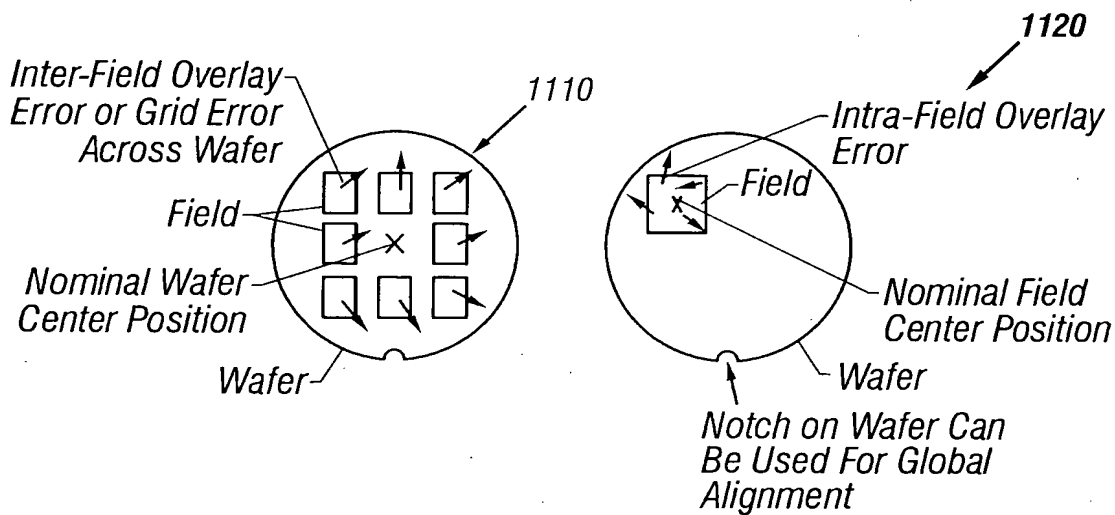


FIG. 11A

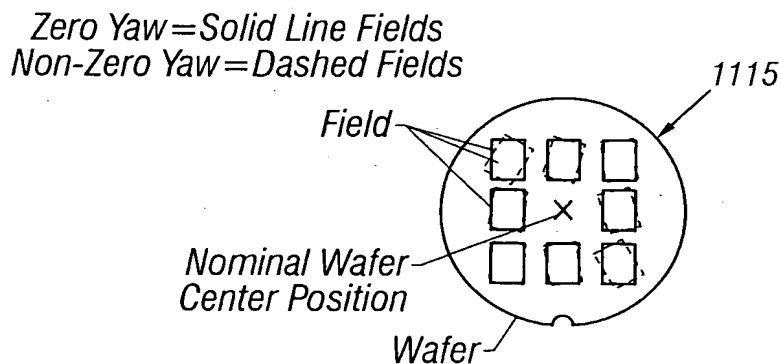
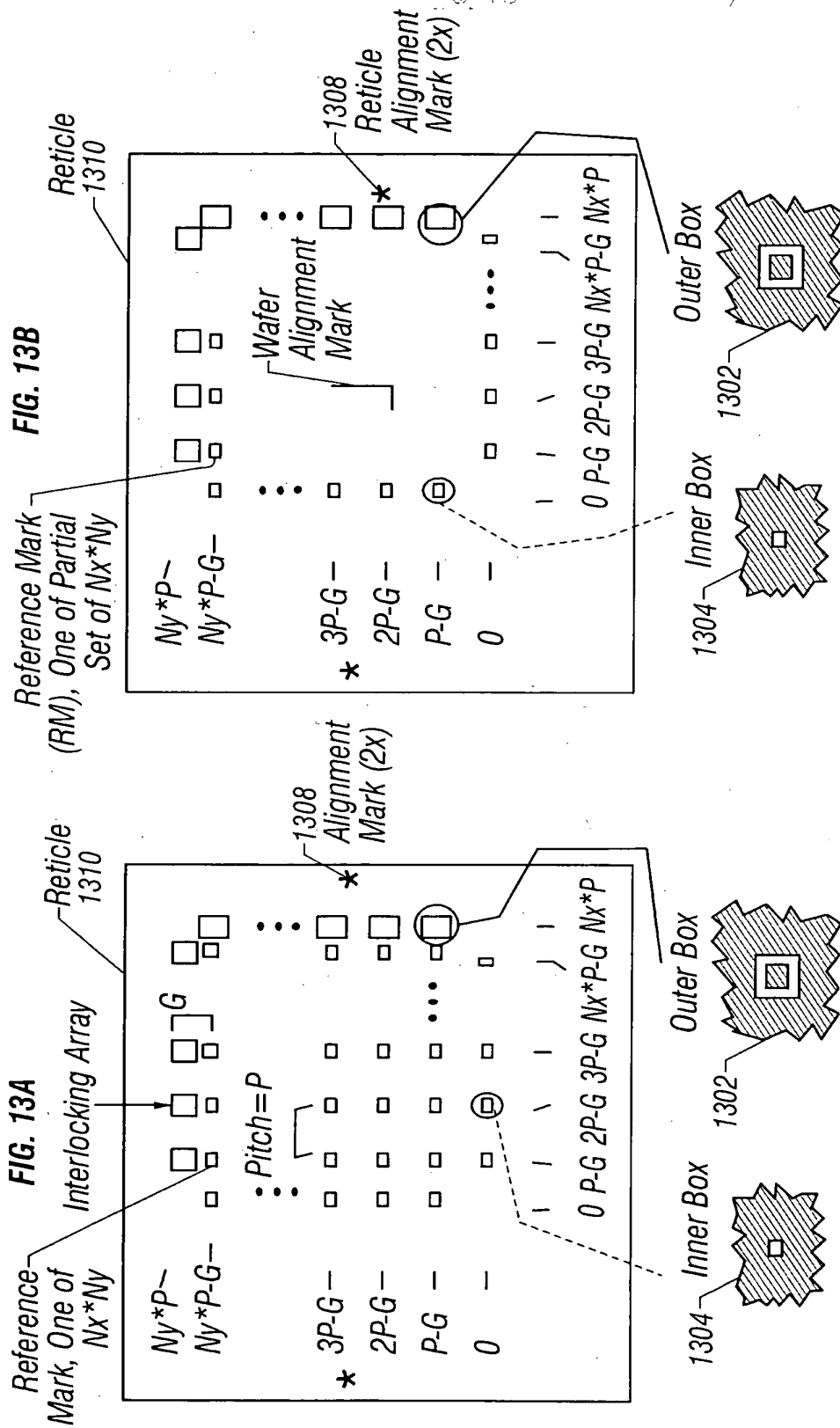


FIG. 11B







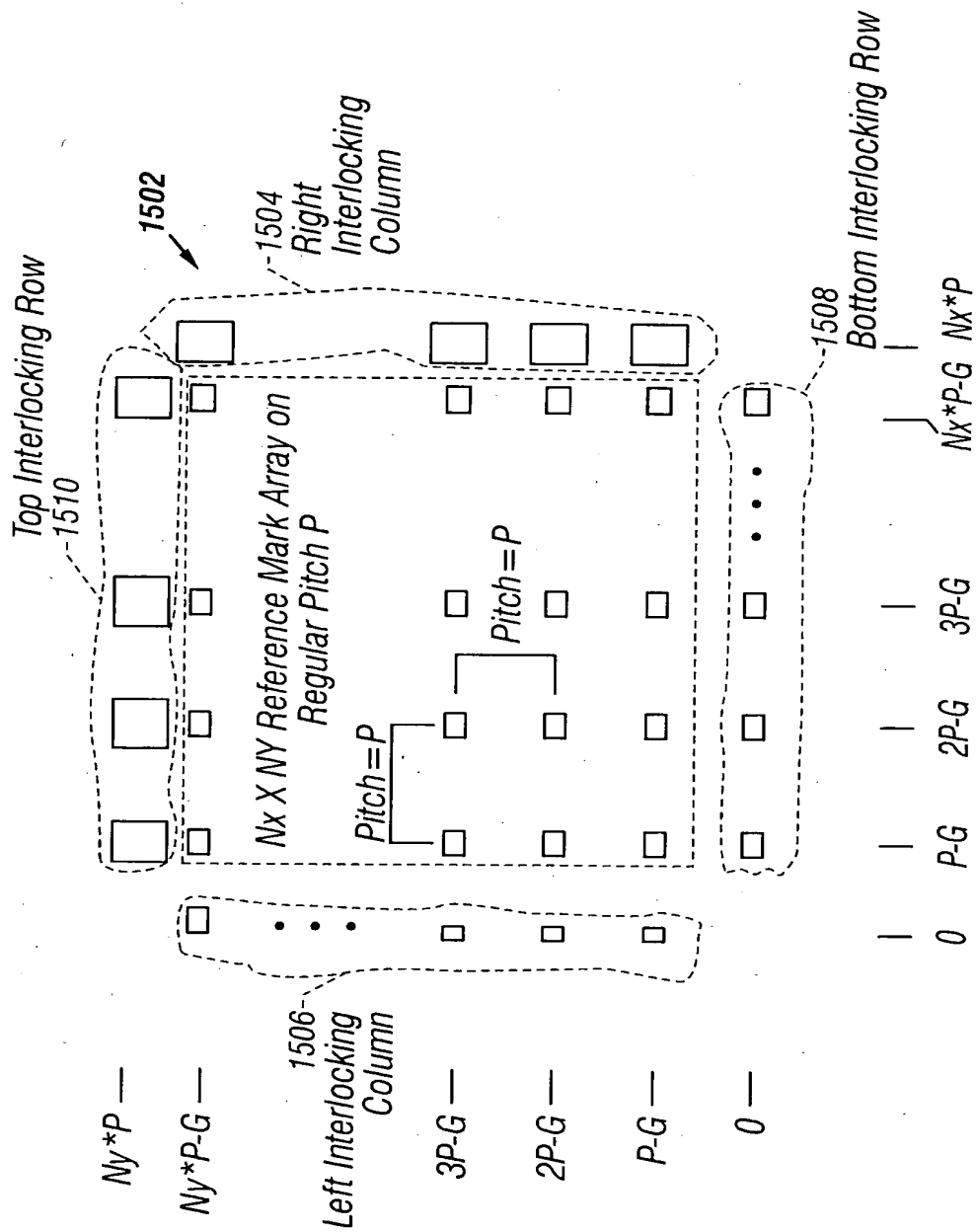
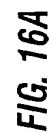
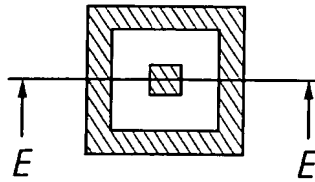
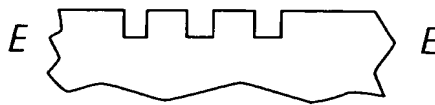


FIG. 15

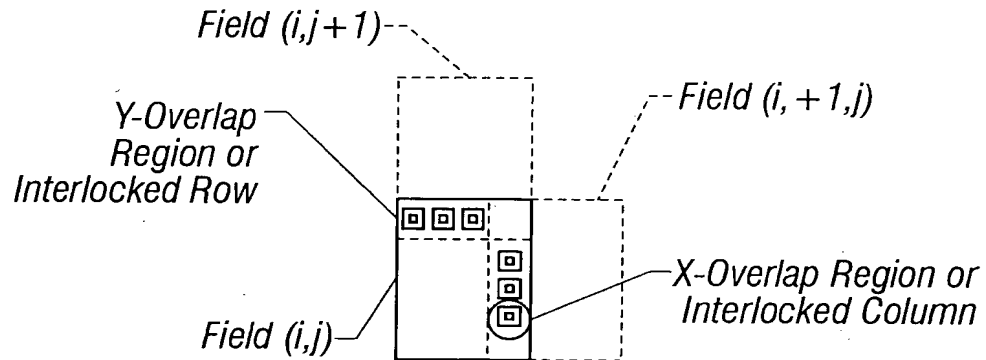




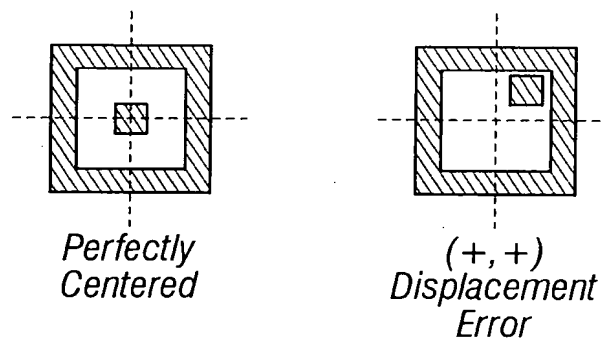
**FIG. 16B**



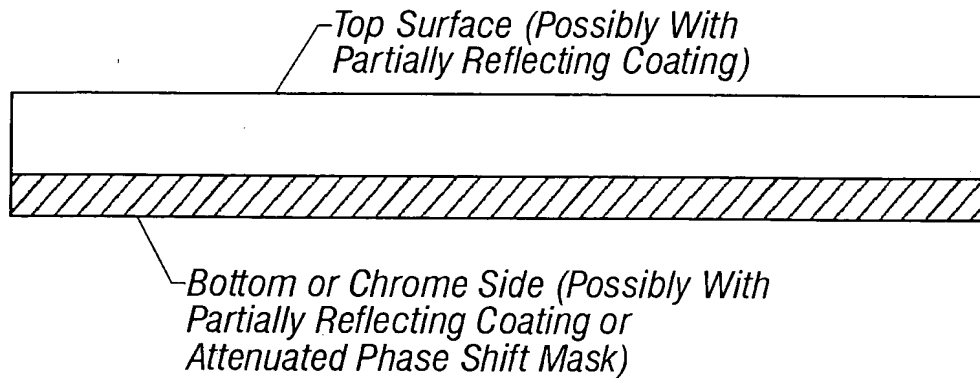
**FIG. 16C**



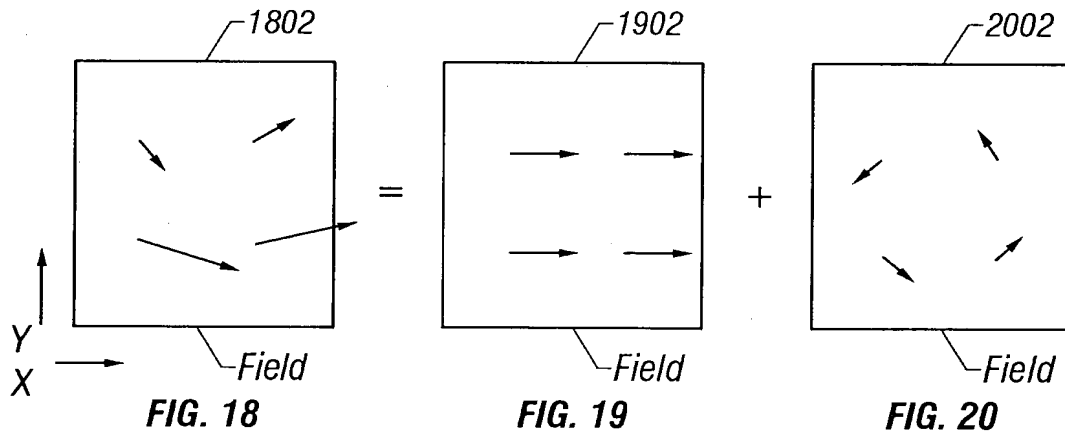
**FIG. 17A**



**FIG. 17B**



**FIG. 14**



**FIG. 21**

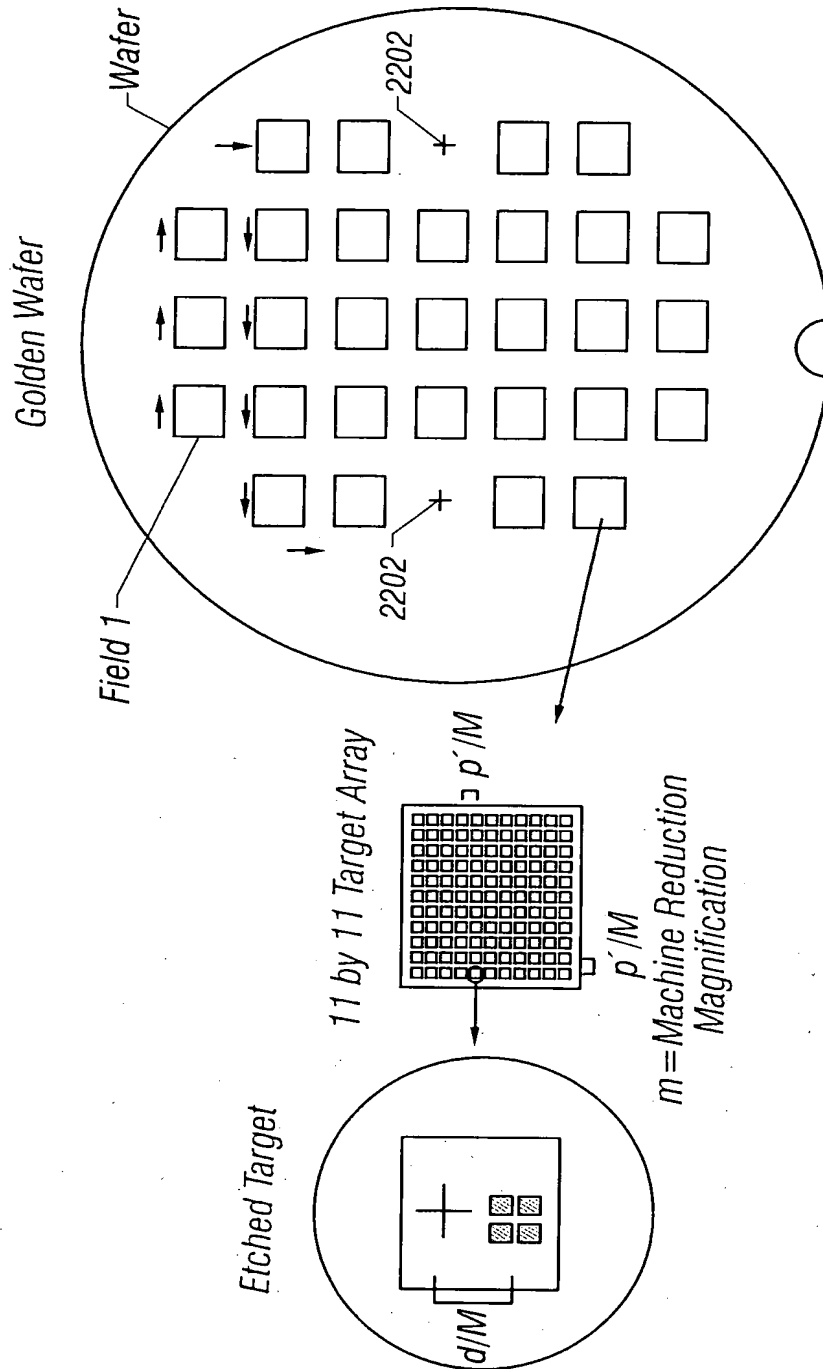
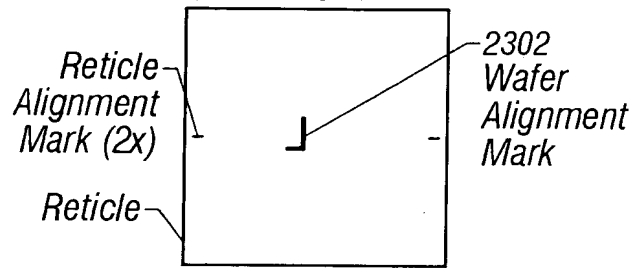
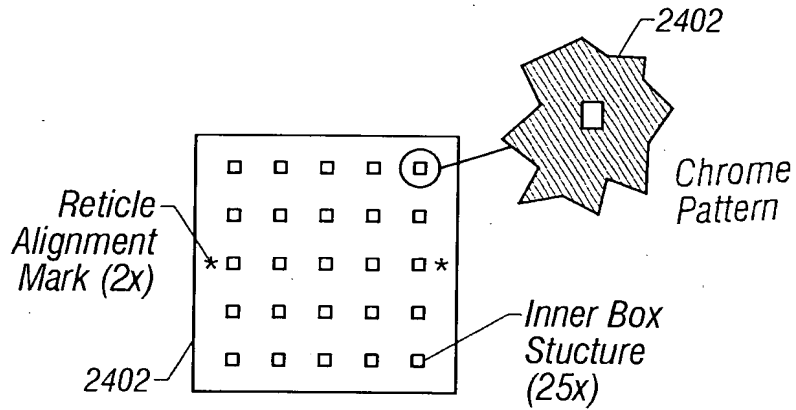


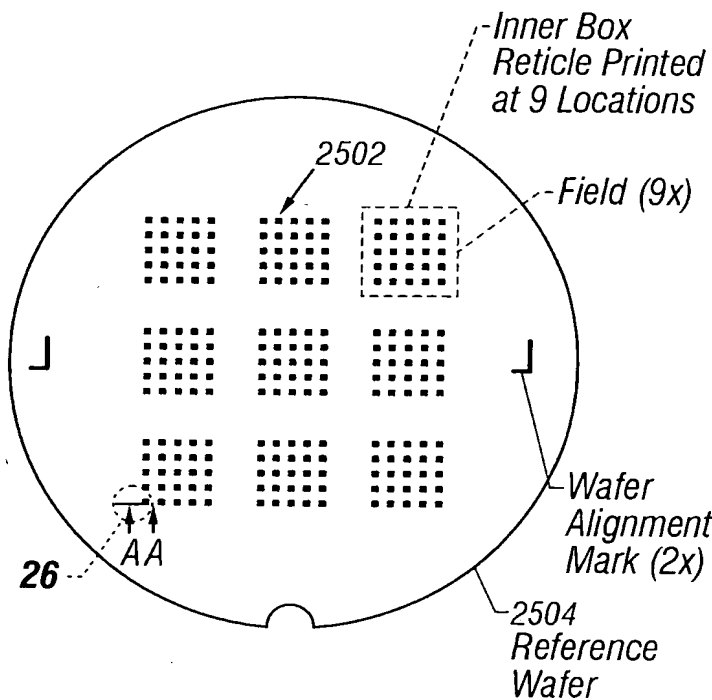
FIG. 22



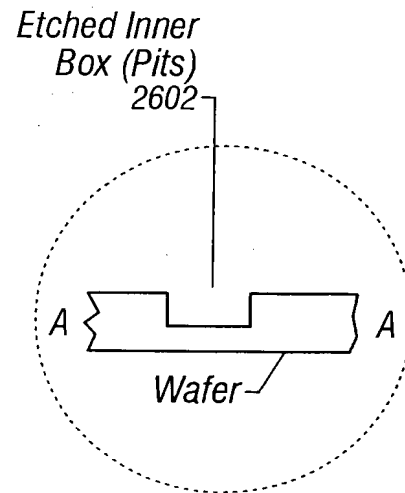
**FIG. 23**



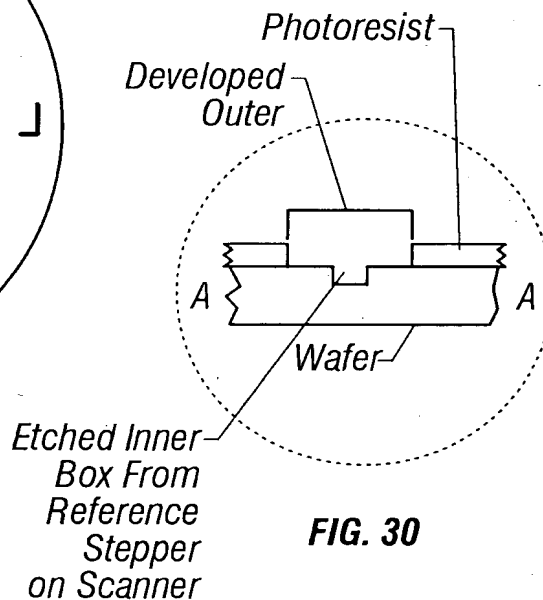
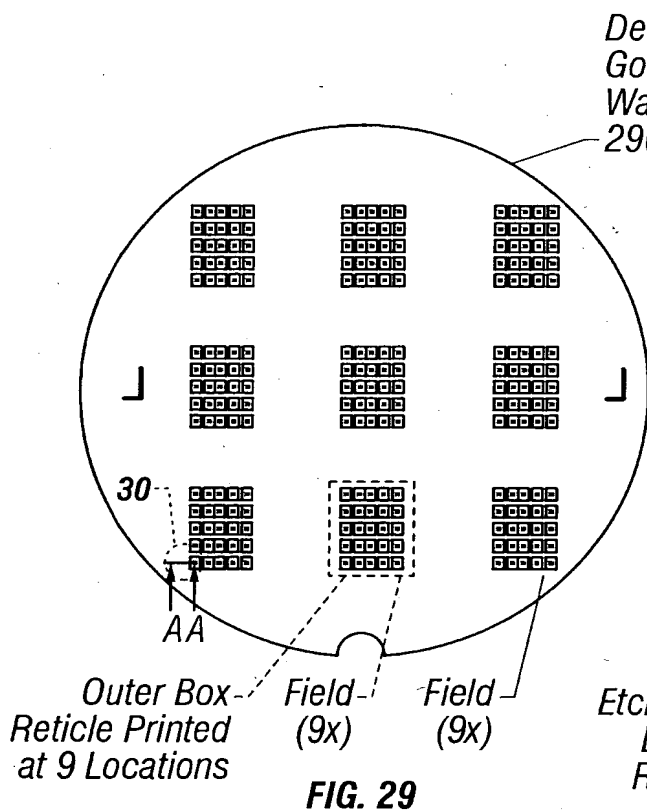
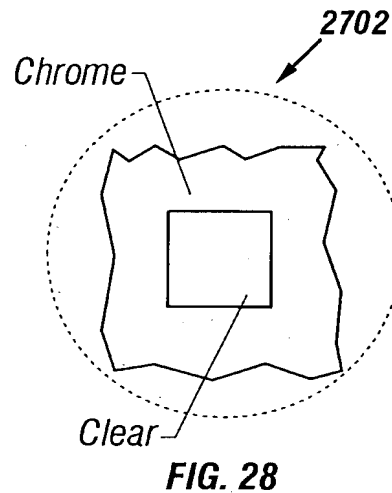
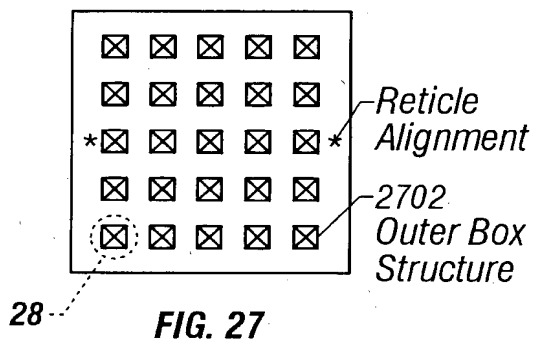
**FIG. 24**

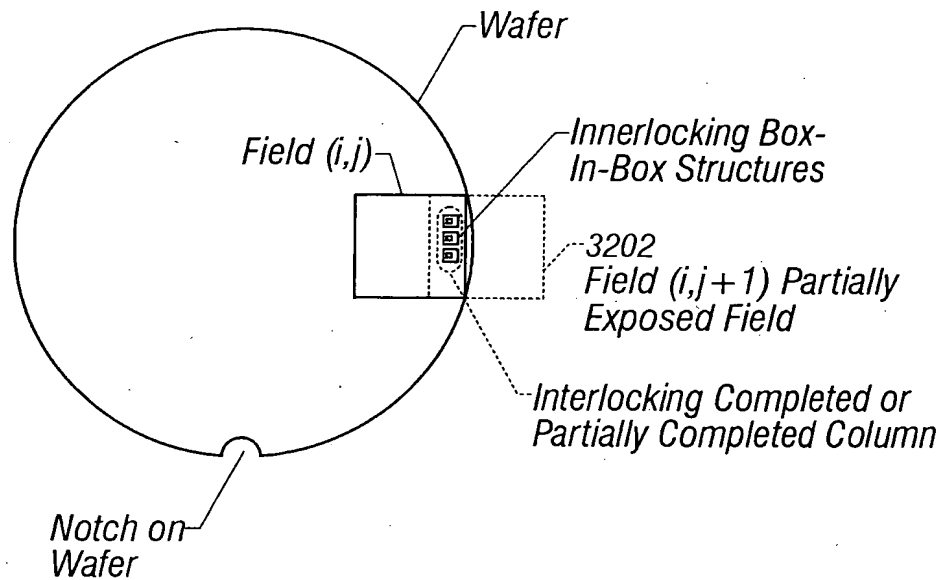
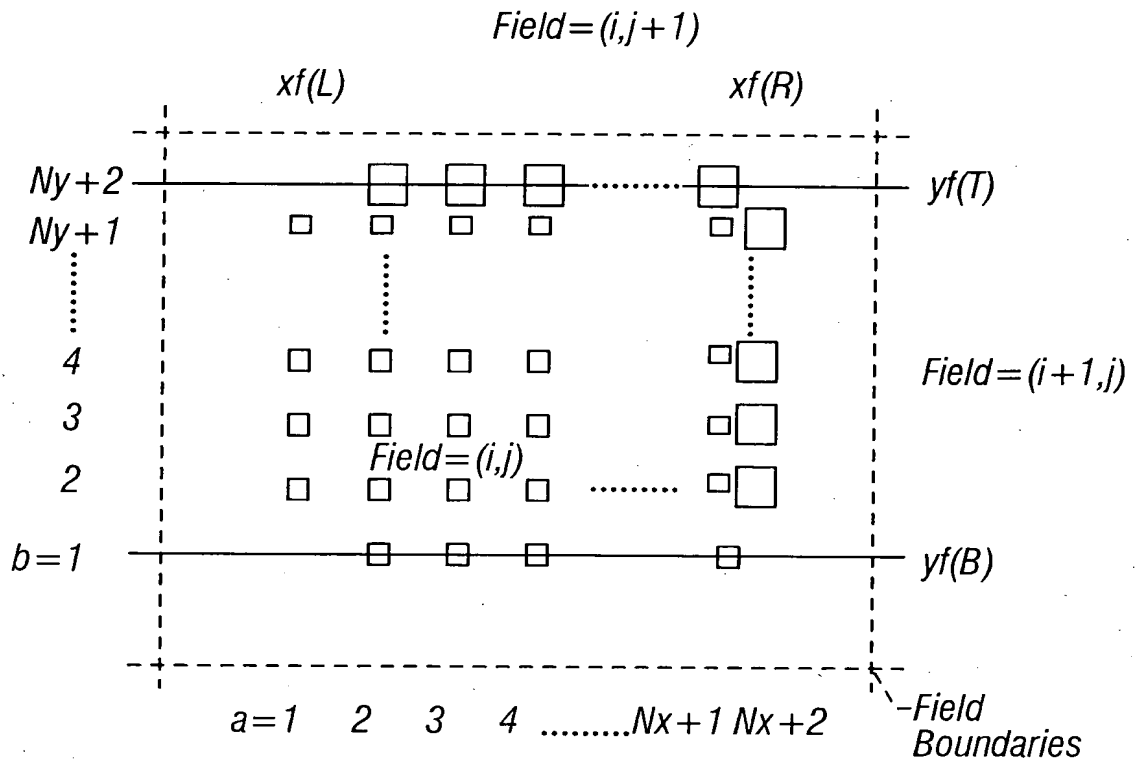


**FIG. 25**

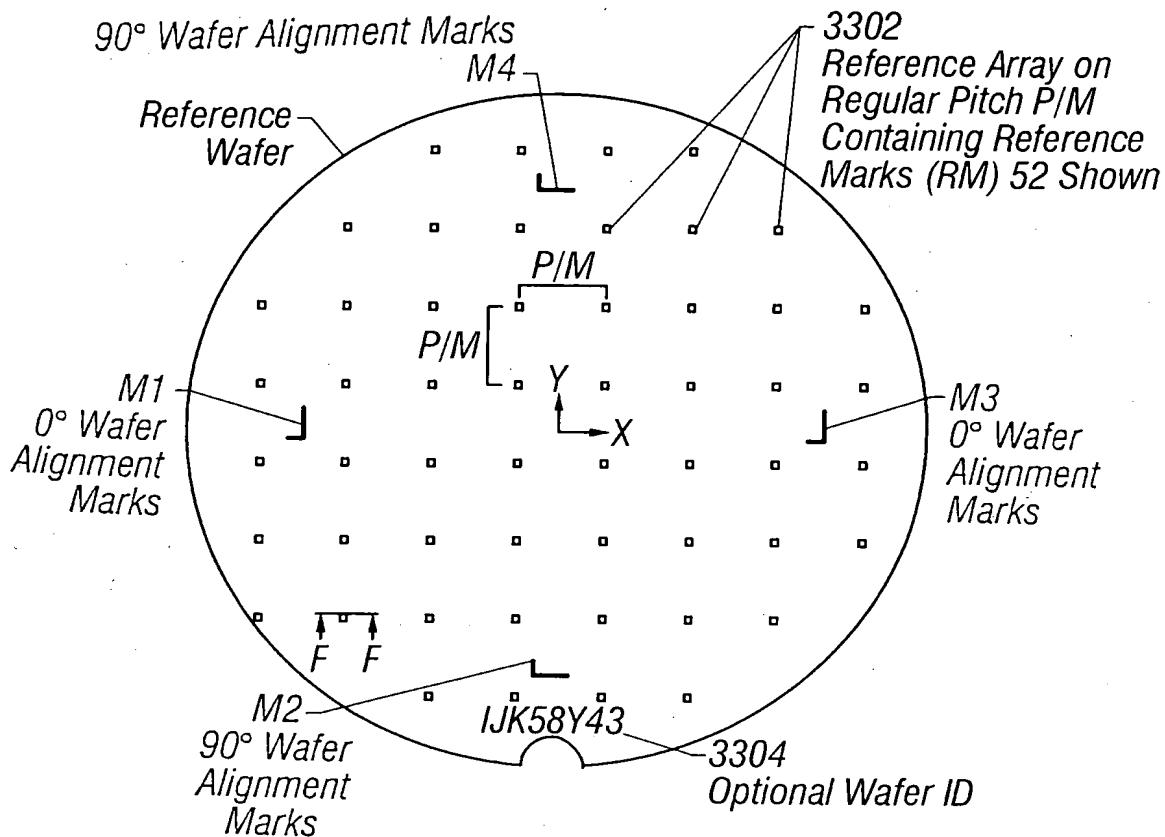


**FIG. 26**







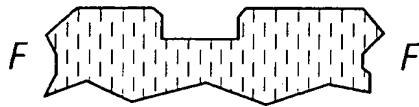


**FIG. 33**

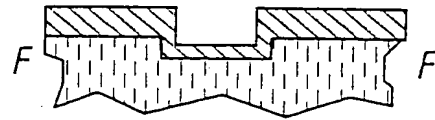
Feature	xG	yG	dx	dy
M1	-95.000000	0.000000	0.000050	-0.000037
M2	0.000000	-95.000000	-0.000387	0.000298
M3	95.000000	0.000000	0.000499	-0.000799
M4	0.000000	95.000000	0.000174	0.000274
RM	10.000000	10.000000	0.000598	0.000420
RM	10.000000	20.000000	0.000495	-0.000229
⋮	⋮	⋮	⋮	⋮
RM	-60.000000	-80.000000	0.000339	0.000449

52  
 Entries For Wafer  
 of Figure 33

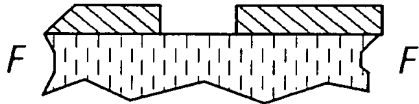
**FIG. 34**



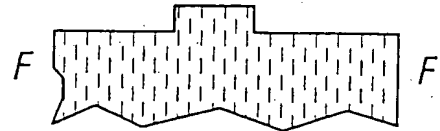
*Pits in Wafer*  
**FIG. 35A**



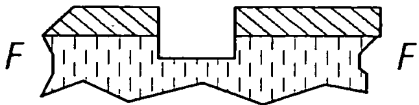
*Pits in Wafer Overcoated*  
**FIG. 35D**



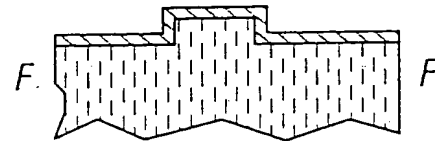
*Pits in Overcoating*  
**FIG. 35B**



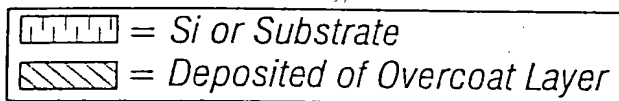
*Mound in Wafer*  
**FIG. 35E**



*Pits in Overcoating & Wafer*  
**FIG. 35C**



*Overcoated Mound on Wafer*  
**FIG. 35F**



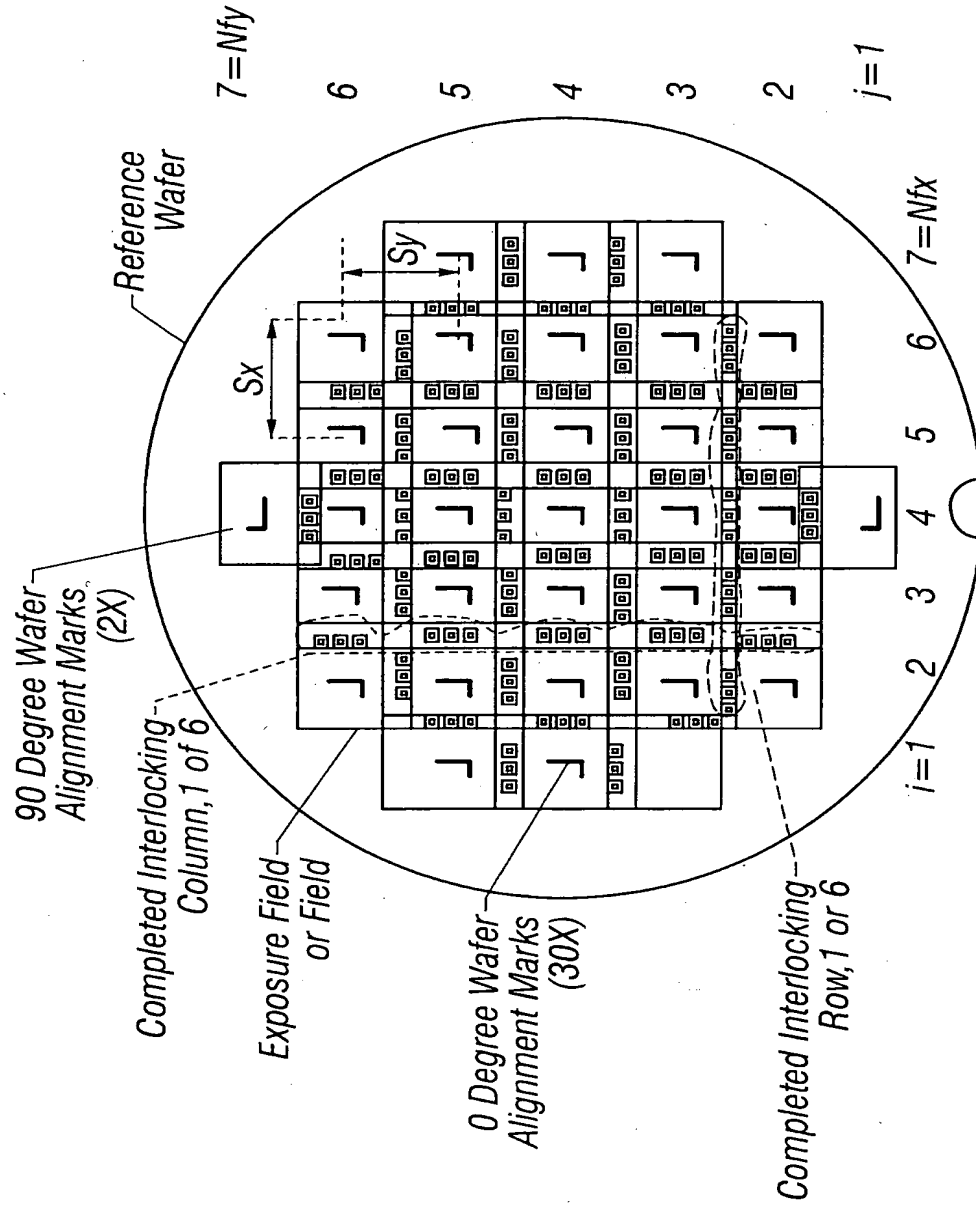


FIG. 36